Package

NS-B2-B-B

Emitter
Collector

Pin Name

3. Base

Marking Symbol: A1

Code

# **DSA4001**

### Silicon PNP epitaxial planar type

For general amplification Complementary to DSC4001 DSA2001 in NS through hole type package

#### Features

- $\bullet$  High forward current transfer ratio  $h_{FE}$  with excellent linearity
- Low collector-emitter saturation voltage V<sub>CE(sat)</sub>
- Contributes to miniaturization of sets, mount area reduction
- Eco-friendly Halogen-free package

#### Packaging

Radial type : 5000 pcs / carton

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Symbol	Rating	Unit				
V <sub>CBO</sub>	-60	V				
V <sub>CEO</sub>	-50	V				
V <sub>EBO</sub>	-7	V				
I <sub>C</sub>	-100	mA				
I <sub>CP</sub>	-200	A				
P <sub>C</sub>	300	mW				
Tj	150	°C				
T <sub>stg</sub>	-55 to +150	°C				
	VCBO       VCEO       VEBO       IC       ICP       PC       Tj	$\begin{array}{c c c c c c c c c c c c c c c c c c c $				

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_{\rm C} = -10 \mu {\rm A}, I_{\rm E} = 0$	-60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$	-50			V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	$I_{\rm E} = -10 \mu {\rm A}, I_{\rm C} = 0$	-7			V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{\rm CB} = -20 \text{ V}, I_{\rm E} = 0$			- 0.1	μΑ
Collector-emitter cutoff current (Base open)	I <sub>CEO</sub>	$V_{\rm CE} = -10$ V, $I_{\rm B} = 0$			-100	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = -10 \text{ V}, I_C = -2 \text{ mA}$	210		460	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_{\rm C} = -100 \text{ mA}, I_{\rm B} = -10 \text{ mA}$		- 0.2	- 0.5	V
Transition frequency	f <sub>T</sub>	$V_{\rm CE} = -10$ V, $I_{\rm C} = -2$ mA		150		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

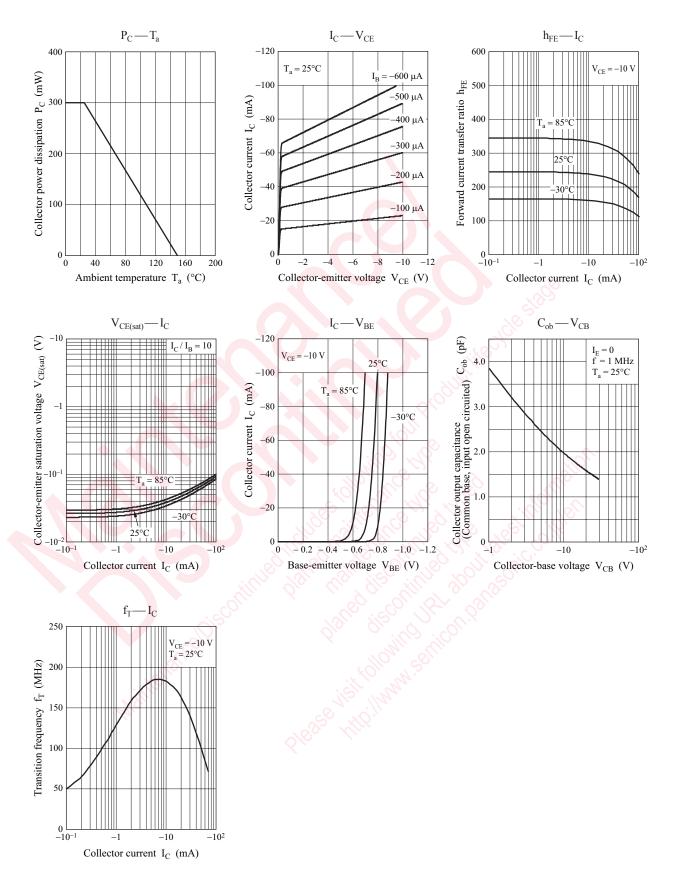
2. \*: Rank classification

Code	R	S	0
Rank	R	S	No-rank
h <sub>FE</sub>	210 to 340	290 to 460	210 to 460
Marking Symbol	A1R	A1S	A1

Product of no-rank is not classified and have no marking symbol for rank.

#### DSA4001

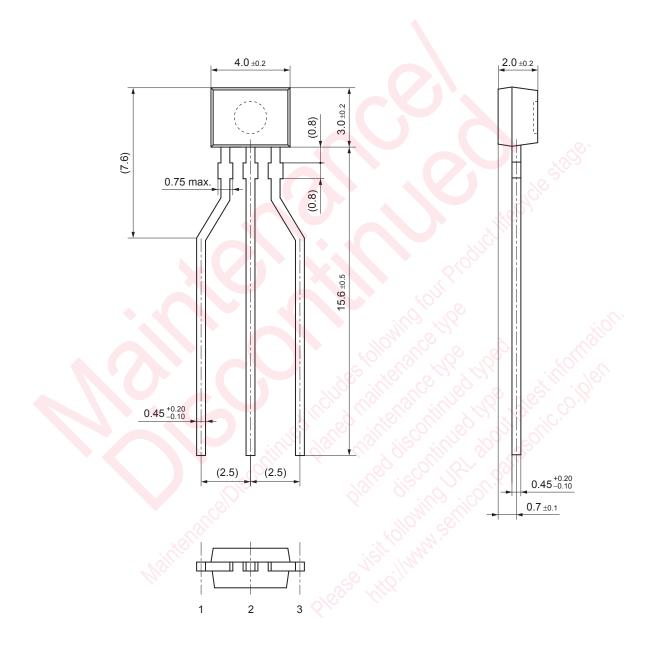
### **Panasonic**



### **Panasonic**

NS-B2-B-B

Unit: mm



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